

INFORMATION DISCLOSURE
STATEMENT BY APPLICANT
Form PTO-1449 (Modified)
Use several sheets if necessary

Sheet 2 of 6

COMPLETELY KNOWN

Application Number	09/885,451
Confirmation Number	3390
Filing Date	February 20, 2001
First Named Inventor	Thomas L. Ritzdorf
Group Art Unit	1741
Examiner Name	Unknown
Attorney Docket No.	29195-8170US2

U.S. PATENT DOCUMENTS

Examiner Initial	U.S. Patent or Application	Name of Patentee or Applicant of Cited Document	Date of Publication or Filing Date of Cited Document	Pages, Columns, Lines, Where Relevant Figures Appear	T
WL	*6,297,154	Gross et al.	10/02/01		

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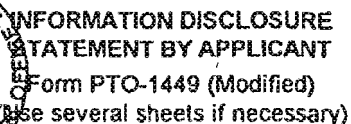
Examiner Initial	Cite No.	Foreign Patent or Application		Name of Patentee or Applicant of Cited Document	Date of Publication or Filing Date of Cited Document	Pages, Columns, Lines, Where Relevant Figures Appear	T
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EXAMINER: William Leader DATE CONSIDERED: 9/9/2004

*EXAMINER: Initial if reference considered, whether or not criteria is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to application(s).

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PTO/SB/08a/b (08-03)
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Substitute for form 1449A/B/PTO		Complete if Known			
INFORMATION DISCLOSURE STATEMENT BY APPLICANT <i>(Use as many sheets as necessary)</i>		Application Number	09/885,451-Conf. #3390		
		Filing Date	June 20, 2001		
		First Named Inventor	Thomas L. Ritzdorf		
		Art Unit	1742		
		Examiner Name	W. T. Leader		
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Examiner Signature	W. Leader	Date Considered	6/7/05
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